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2 Channel EMI Filter with ESD Protection for Headset Microphone Applications

Features

- 2 channels of EMI filtering
- Pi-style filters in a capacitor-resistor-capacitor (C-R-C) network
- 8kV ESD protection (IEC 61000-4-2, contact discharge)
- 15kV ESD protection (HBM)
- Supports AC signals ideal for audio applications
- Greater than 40dB of attenuation at 1GHz
- 8-lead, 2.00mm x 2.00mm footprint TDFN Package
- Low profile maximum height of 0.8mm
- Lead-free finishing

Applications

- Headset Microphone port in mobile handsets
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.



Electrical Schematic



PIN DESCRIPTIONS					
PIN	NAME	DESCRIPTION			
1	Filter #1	Filter #1			
2	NC	No connect			
3	NC	No connect			
4	Filter #2	Filter #2			
5	Filter #2	Filter #2			
6	NC	No connect			
7	NC	No connect			
8	Filter #1	Filter #1			
DAP	GND	Ground			

Ordering Information

PART NUMBERING INFORMATION					
		Lead-free Finish			
Pins	Package	Ordering Part Number ¹	Part Marking		
8	TDFN	CM1482-02DE	82E		

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

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Specifications

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	RATING	UNITS			
Storage Temperature Range	-65 to +150	°C			
DC package power rating	0.5	W			

STANDARD OPERATING CONDITIONS					
PARAMETER	RATING	UNITS			
Operating Temperature Range	-40 to +85	°C			

ELECTRICAL OPERATING CHARACTERISTICS (NOTE 1)								
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS		
R	Resistance R		61	68	75	Ω		
R _{MATCH}	Resistor-to-Resistor Matching	Note 3			5	%		
C _{TOT}	Total Channel Capacitance	2.5V DC; 1MHz, 30mV AC	74	94	114	pF		
С	Capacitance C			47		pF		
I _{LEAK}	Diode Leakage Current	$V_{IN} = \pm 5.0 V$		0.1	1.0	μA		
V _{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	$I_{LOAD} = 10mA$ $I_{LOAD} = -10mA$	5 –15	7 -10	15 5	V V		
V _{ESD}	In-system ESD Withstand Voltage Human Body Model, MIL-STD-883, Method 3015 Contact Discharge per IEC 61000-4-2 Level 4	Notes 2 & 3	±15 ±8			kV kV		
f _C	Cut-off frequency $Z_{SOURCE} = 50\Omega$, $Z_{LOAD} = 50\Omega$	R = 68Ω, C = 47pF		60		MHz		

Note 1: $T_A = 25^{\circ}C$ unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to GND, one at a time. Clamping voltage is measured at the opposite side of the EMI filter to the ESD pin (i.e. if ESD is applied to pin 1 then clamping voltage is measured at pin 8).

Note 3: These parameters guaranteed by design and characterization.

Performance Information

Typical Filter Performance (nominal conditions unless specified otherwise, 50 ohm environment)





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Mechanical Details

TDFN-08 Mechanical Specifications, 0.5mm

The CM1482 is supplied in an 8-lead 0.5mm TDFN package. Dimensions are presented below.

For complete information on the TDFN-08, see the California Micro Devices TDFN Package Information document.

PACKAGE DIMENSIONS							
Package	TDFN						
JEDEC No.	MO-229 (Var. VCCD-3) [*]						
Leads	8						
Dim	Millimeters			Inches			
Dini.	Min	Nom	Max	Min	Nom	Max	
Α	0.70	0.75	0.80	0.028	0.030	0.031	
A3	0.20 REF			0.008 REF			
b	0.20	0.25	0.30	0.008	0.010	0.012	
D	1.90	2.00	2.10	0.075	0.079	0.083	
D2	1.50	1.60	1.70	0.059	0.063	0.067	
Е	1.90	2.00	2.10	0.075	0.079	0.083	
E2	0.80	0.90	1.00	0.031	0.035	0.039	
е	0.50 BSC			0	0.020 BSC		
К	0.20			0.008			
L	0.20	0.30	0.40	0.008	0.012	0.016	
# per tape and reel			3000	pieces			
Controlling dimension: millimeters							

^{*}This package is compliant with JEDEC standard MO-229, variation VCCD-3 with exception of the D2 and E2 dimensions as called out in the table above and the r1 dimension which is not specified in the MO-229 standard.



Package Dimensions for 8-Lead, 0.5mm pitch TDFN package

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